

|   | Type | L # | Hits | Search Text  | DBs   | Time Stamp          | C<br>o<br>m<br>m<br>e<br>n<br>t<br>s | E<br>r<br>r<br>o<br>r<br>s | E<br>r<br>r<br>o<br>r<br>s |
|---|------|-----|------|--|---|---------------------|--------------------------------------|----------------------------|----------------------------|
| 1 | BRS  | L1  | 148  | ((organic) with (dielectric or insulat\$3)) with<br>(etch adj stop\$4)                                 | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/06/11<br>15:33 |                                      |                            | 0                          |
| 2 | BRS  | L8  | 148  | 1 same etch\$3   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/06/11<br>12:07 |                                      |                            | 0                          |
| 3 | BRS  | L15 | 28   | 8 and @pd<=20000430  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/06/11<br>13:11 |                                      |                            | 0                          |
| 4 | BRS  | L22 | 4    | 15 and damascene   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/06/11<br>15:38 |                                      |                            | 0                          |
| 5 | BRS  | L29 | 38   | 5,565,384  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/06/11<br>13:07 |                                      |                            | 0                          |
| 6 | BRS  | L36 | 0    | etch\$4 with (via or opening or hole) with<br>trench with (organic adj (dielectric or<br>insulati\$3)) | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/06/11<br>13:10 |                                      |                            | 0                          |
| 7 | BRS  | L43 | 17   | etch\$4 with (via or opening or hole) with<br>trench with (organic adj (dielectric or<br>insulati\$3)) | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/06/11<br>17:10 |                                      |                            | 0                          |
| 8 | BRS  | L57 | 0    | 50 and @pd<=20000430   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/06/11<br>16:41 |                                      |                            | 0                          |

|    | Type | L # | Hits | Search Text   | DBs   | Time Stamp          | C<br>o<br>m<br>m<br>e<br>n<br>t<br>s | E<br>r<br>r<br>o<br>r<br>D<br>e<br>f<br>i<br>n<br>i<br>t<br>i<br>o<br>n | E<br>r<br>r<br>o<br>r<br>s |
|----|------|-----|------|---|---|---------------------|--------------------------------------|---|----------------------------|
| 9  | BRS  | L50 | 17   | etch\$4 with (via or opening or hole) with trench with (organic adj (dielectric or insulat\$3))   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/06/11<br>13:12 |                                      |   | 0                          |
| 10 | BRS  | L64 | 78   | (inorganic) with (dielectric or insulat\$3) with (etch adj stop\$4)                               | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/06/11<br>15:34 |                                      |   | 0                          |
| 11 | BRS  | L71 | 57   | 64 and damascene  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/06/11<br>15:38 |                                      |   | 0                          |
| 12 | BRS  | L78 | 6    | 71 and @pd<=20000430  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/06/11<br>16:41 |                                      |   | 0                          |
| 13 | BRS  | L85 | 22   | etch\$4 with (via or opening or hole) with trench with (inorganic adj (dielectric or insulat\$3)) | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/06/11<br>17:11 |                                      |   | 0                          |